

xLED

xLED-SEO-6050 Pin Fin Heat Sink Φ 60mm for Seoul

Features VS Benefits

- * The xLED-SEO-6050 Seoul Pin Fin LED Heat Sinks are specifically designed for luminaires using the Seoul LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 900 to 2,200 lumen.
- * Thermal resistance range Rth 3.85°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Seoul COB series and AC Modules.
- * Diameter 60.0mm - standard height 50.0mm, Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Seoul COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



Seoul LED Modules directly Mounting Options

Seoul COB Series, Size 13.5x13.5mm.

SAW80661A;	SDW01F1C;
SAW90661A;	SDW81F1B;
SAW810xxx;	SDW81F1C;
SAW910xxx;	SDW81F1DY;

With the Zhaga Book 11 holders for the green indicator marks.
 BJB holder: 47.319.6294.50; AAG.STUCCHI: 8100-G2
 Without the holders for the pink indicator marks.
 Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:
 Olivia series: FN14637-S
 Ronda series: FN15972-xxx; FN15971-xxx; FN15969-xxx;

Seoul COB Series, Size 19x19mm.

SDW02F1C;	SDW82F1C;
SDW03F1C;	SDW83F1C;
SDW92F1C;	

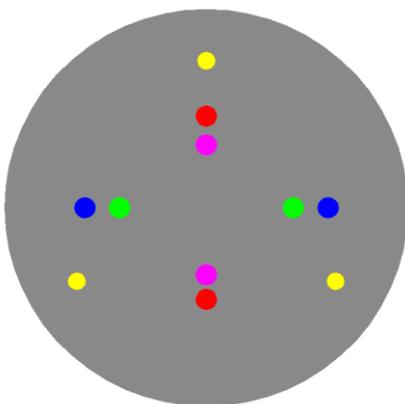
With the Zhaga Book 3 holders for the blue indicator marks.
 BJB holder: 47.319.2021.50; AAG.STUCCHI: 8101-G2
 Without the holders for the red indicator marks.
 Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:
 Olivia series: FN14637-S; FN14828-M;
 Ronda series: FN15xxx-xx;

AC LED Modules, Size Φ 46mm.

SMJE-2D08W 4PD;	SMJD-3D08W 4PD;
SMJE-2D08W 4PE;	SMJD-3D08W 4PE;
SMJE-2D12W 4PD;	SMJD-3D12W 4PD;
SMJE-2D12W 4PE;	SMJD-3D12W 4PE;

Direct mounting with 3 screws M2x6.5mm.
 Yellow indicator marks.



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Mounting Options and Drawings & Dimensions

Example: xLED-SEO-6050-B-1,2

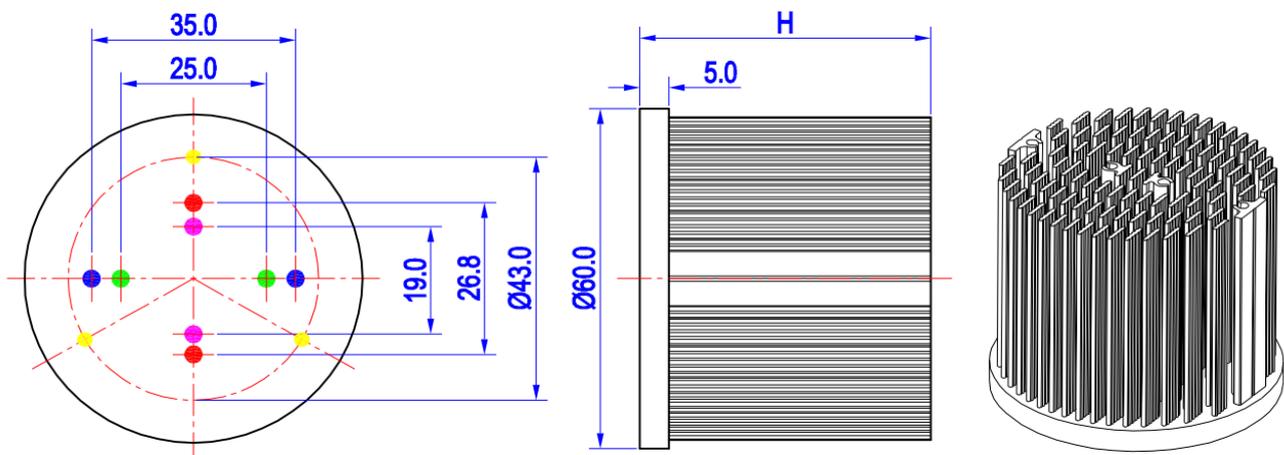
Example: xLED-SEO-60 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
 - B-Black
 - C-Clear
 - Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
Ex.order code - 12
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Olivia series	Ronda series			
1	COB Size 13.5x13.5mm	/	FN14637-S;	FN15972-xxx; FN15971-xxx; FN15969-xxx;	M3	6.5mm	19.0mm/ 2-@180°
2		BJB Holder 47.319.2021.50 AAG.STUCCHI 8101-G2			M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
3	COB Size 19x19mm	/	FN14637-S; FN14828-M;	FN15xxx-xx;	M3	6.5mm	26.8mm/ 2-@180°
4		BJB Holder 47.319.2021.50 AAG.STUCCHI 8101-G2			M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
5	AC Module	/	/	/	M2	6.5mm	43.0mm/ 3-@120°



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The product data table

	Model No.	xLED-SEO-6050
	Heatsink Size	$\Phi 60 \times H 50\text{mm}$
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	112.0
	Dissipated power (Ths-amb,50°C)	13.0 (W)
	Cooling surface area (mm²)	68473
	Thermal Resistance (Rhs-amb)	3.85 (°C/W)

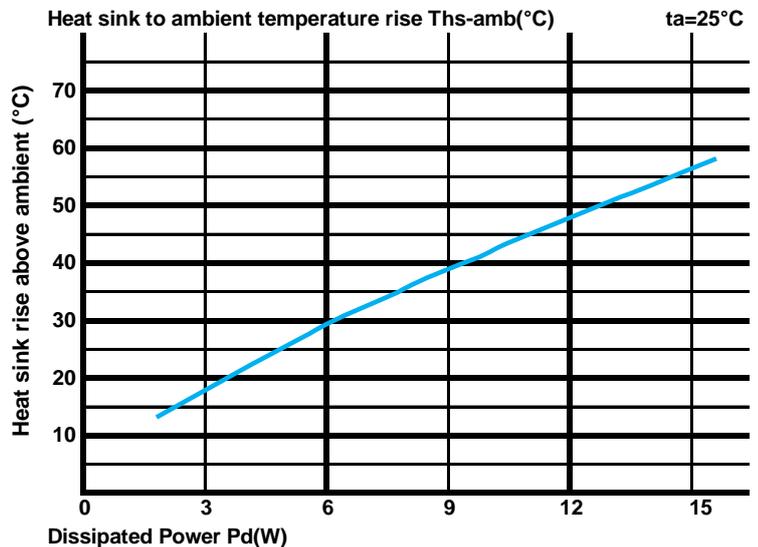
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

* To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

Pd - Dissipated power ; Pe - Electrical power ; η_L = Light efficiency of the LED module;

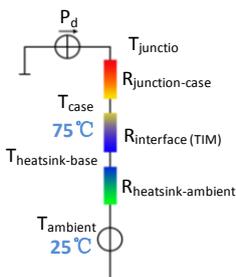
Dissipated Power Pd(W)	Pd = Pe x (1- η_L)	Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-SEO-6050	
3.0		5.67	17.0
6.0		4.83	29.0
9.0		4.22	38.0
12.0		4.00	48.0
15.0		3.73	56.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [°C/W], the thermal resistance with the heat sink is $R_{\text{heatsink-ambient}}$ [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package $R_{\text{interface (TIM)}}$ and $R_{\text{heatsink-ambient}}$ can be integrated into the thermal resistance $R_{\text{case-ambient}}$ at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$